

TANK-871-Q170

- High-Performance 6th/7th Generation Intel® Core™ Processor
- Fanless Embedded Computer

Features

- 6th/7th Gen Intel® Core™ processor platform with Intel® Q170 chipset and DDR4 memory
- Triple independent display with high resolution support
- Rich high-speed I/O interfaces on one side for easy installation

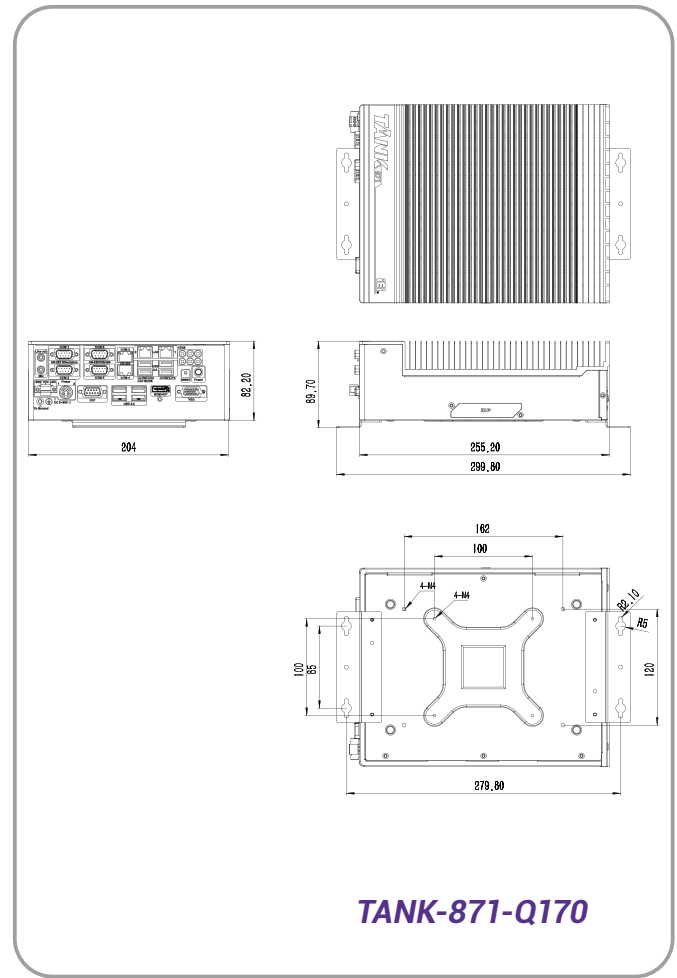
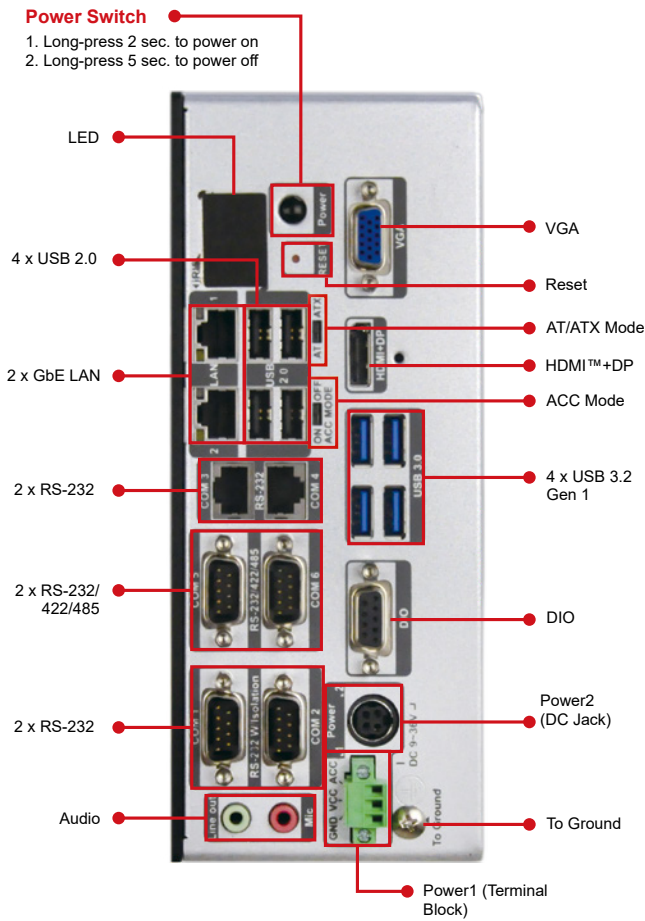


Specifications

Model Name		TANK-871-Q170
Chassis	Color	Black C + Silver
	Dimensions (WxDxH) (mm)	82.2 x 255.2 x 204
	System Fan	Fanless
	Chassis Construction	Extruded aluminum alloy
Motherboard	CPU	7 th Gen Intel® Core™ CPU & Intel® Core™ i7-6700TE 2.4 GHz (up to 3.4 GHz, quad-core, TDP 35) Intel® Core™ i5-6500TE 2.3 GHz (up to 3.3 GHz, quad-core, TDP 35)
	Chipset	Intel® Q170
	System Memory	2 x SO-DIMM DDR4 2133 (4GB pre-installed) (up to 32GB)
Storage	Hard Drive	2 x 2.5" SATA 6Gb/s HDD/SSD bay (RAID 0/1 support)
I/O Interfaces	USB	4 x USB 3.2 Gen 1 4 x USB 2.0
	Ethernet	2 x RJ-45: LAN1: GbE by Intel® I219LM LAN2: GbE by Intel® I210
	COM Port	2 x RS-232/422/485 with AFC (DB-9) 4 x RS-232 (2 x RJ-45, 2 x DB-9 with 2.5kV isolation)
	Digital I/O	8-bit Digital I/O (4-in/ 4-out)
	Display	1 x VGA (up to 1920 x 1200@60Hz) 1 x HDMI™/DP (up to 3840 x 2160@30Hz /4096×2304@60Hz) 1 x iDP (optional)
	Audio	1 x Line-out, 1 x Mic-in
	Wireless	1 x 802.11a/b/g/n/ac (optional)
	TPM	1 x TPM 2.0 (2 x 10 pin) (optional)
Expansions	PCIe Mini	1 x Half-size (PCIe/ USB 2.0) 1 x Full-size (PCIe/ USB 2.0/ SATA)
Power	Power Input	DC Jack: 9 ~ 36V DC Terminal Block: 9 ~ 36V DC
	Power Consumption	19V@3.68A (Intel® Core™ i7-6700TE with 8GB memory)
Reliability	Mounting	Wall mount
	Operating Temperature/Humidity	i7-6700TE: -20°C ~ 45°C with air flow (SSD), 10% ~ 95% non-condensing i5-6500TE: -20°C ~ 60°C with air flow (SSD), 10% ~ 95% non-condensing
	Storage Temperature/Humidity	-40°C ~ 85°C with air flow (SSD), 10% ~ 95% non-condensing
	Operating Shock	Half-sine wave shock 5G, 11ms, 100 shocks per axis (SSD)
	Operating Vibration	MIL-STD-810G 514.6 C-1 (SSD)
	Weight (Net/Gross)	3.5 kg/4.5 kg
	Safety/EMC	CE/FCC/KC
OS	Supported OS	Microsoft® Windows® 8 Embedded, Microsoft® Windows® Embedded Standard 7 E, Microsoft® Windows® 10 IoT Enterprise

Fully Integrated I/O

Dimensions (Unit: mm)



TANK-871-Q170

Ordering Information

Part No.	Description
TANK-871-Q170-I7/4G-R11	Ruggedized Fanless embedded system with Intel® Core i7-6700TE 2.4GHz, (up to 3.4 GHz, Quad Core, TDP 35W), 4GB DDR4 pre-installed memory, VGA/HDMI+DP/iDP, 9~36V DC, Powder paint, RoHS
TANK-871-Q170-I5/4G-R11	Ruggedized Fanless embedded system with Intel® Core i5-6500TE 2.3GHz, (up to 3.3 GHz, Quad Core, TDP 35W), 4GB DDR4 pre-installed memory, VGA/HDMI+DP/iDP, 9~36V DC, Powder paint, RoHS

Options

Part No.	Description
32000-000002-RS	European power cord
63040-010120-300-RS	Adapter Power;FSP;FSP120-AHAN3;9NA1206708;Active PFC;Vin:90 ~ 264VAC;120W;Dim:75.6*151.3*25.4mm;Plug=6.5mm;Cable=1500mm;Erp(NO LOAD 0.15W);Vout:12VDC;Din 4Pin/lock;CCL;RoHS
EMB-WIFI-KIT01-R20	1T1R wifi module kit for embedded system, IEEE802.11a/b/g/n/ac WiFi with Bluetooth 4.0/3.0+HS, 1 x wifi module, 2 x 250mm RF cable, 2 x Antenna, RoHS
TANK-870-Q170-WES7E64-R10	OS Image with Windows® Embedded Standard 7 E 64-bit for TANK-870-Q170 Series, with DVD-ROM, RoHS
TANK-870-Q170-W10E64-H-R10	OS Image with Windows® Embedded Standard 10 E High End 64-bit for TANK-870-Q170-I7 Series, with DVD-ROM, RoHS
TANK-870-Q170-W10E64-V-R10	OS Image with Windows® Embedded Standard 10 E Value 64-bit for TANK-870-Q170-I5 Series, with DVD-ROM, RoHS
TPM-IN02-R20	20-pin Infineon TPM2.0 module, software management tool, firmware v5.5

Packing List

1 x Chassis Screw	1 x Mounting Bracket
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